

JCT81 U.S. PTO
10/027919
12/20/01

156

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10027919	12/20/2001	205	291	1741	Wong

**APPLICANTS: Seita Masaru; Tsuchida Hideki; Hayashi Shinjiro;

1453

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 2000-387865 12/20/2000

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

51343

TITLE : Electrolytic copper plating solution and method for controlling the same

U.S. DEPT. OF COMM /PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED		
		Total Claims		Print Claim for O.G
Assistant Examiner				
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.	Print Fig.
		Primary Examiner		
		Application Examiner		
<input checked="" type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE		
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.				

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)

BEST AVAILABLE COPY